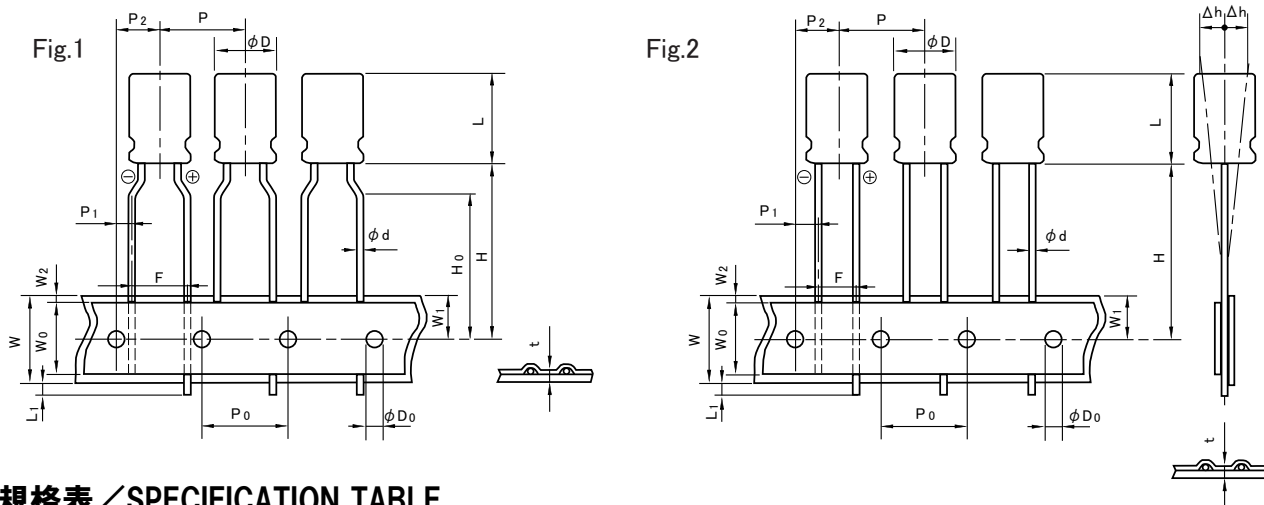


◆テーピング仕様/TAPING SPECIFICATIONS

◆ラジアルリード形(04形)テーピング形状寸法図/DIMENSIONS



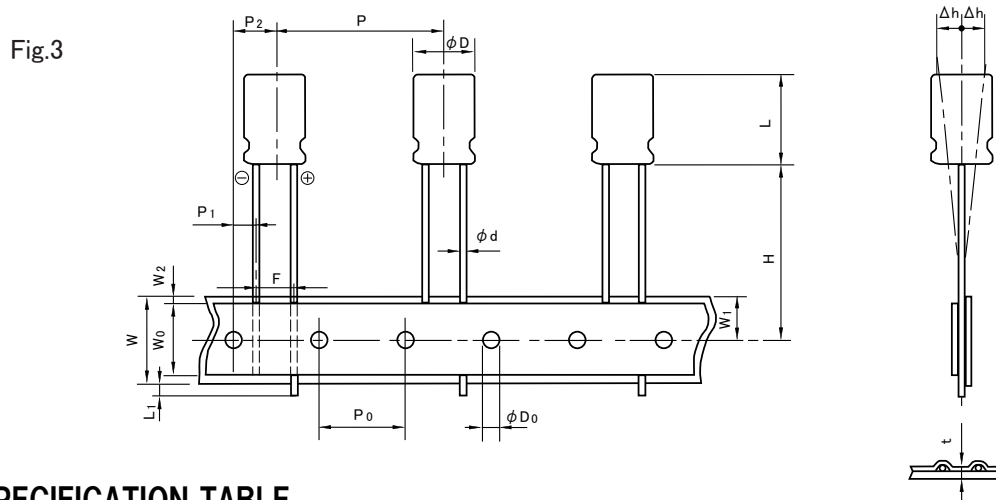
◆規格表/SPECIFICATION TABLE

項目 Item	記号 Code	5mmHeight		7mm or 7.5mm Height				※許容差 Tolerance
		φ4~φ8		φ4~φ6.3	φ4~φ6.3	φ8		
リード加工記号 Taping code		T5	TZ	T5	TZ	TA	T7	
形状寸法図 Applicable Fig. No.		Fig.2	Fig.1	Fig.2	Fig.1	Fig.1	Fig.2	
リード線径 Dia. of lead	φ d	0.45		0.45				±0.05
本体高さ Height of body	L	6.5		8.5				MAX
ボディーピッチ Distance from center to center of next body	P	12.7		12.7				±1.0
送り穴ピッチ Distance from center to center of next driving hole	P ₀	12.7		12.7				±0.2
送り穴位置ズレ (台紙上端との界面にて規定) Distance between center of driving hole and lead (at the upper edge of the carrier tape)	P ₁	5.1	3.85	5.1	3.85	4.6	±0.5	
送り穴位置ズレ Distance between center of driving hole and body	P ₂	6.35		6.35				±1.0
リードピッチ (台紙上端との界面にて規定) Pitch of lead (at the upper edge of the carrier tape)	F	2.5	5.0	2.5	5.0	3.5	+0.8 -0.2	
台紙幅 Width of mounting tape	W	18.0		18.0				±0.3
粘着テープ幅 Width of adhesive tape	W ₀	5.0		5.0				MIN
送り穴位置ズレ Distance between center of driving hole and mounting tape edge	W ₁	9.0		9.0				±0.5
粘着テープズレ Max. allowable distance between mounting and adhesive tape edges	W ₂	1.5		1.5				MAX
ボディ下面位置 Distance between center of driving hole and bottom of body	H	17.5		17.5		20.0		±0.75
リードクリンチ高さ Distance between center of driving hole and clinch part of lead	H ₀	-	16.0	-	16.0		-	±0.5
リード線はみ出し End of lead	L ₁	0.5		0.5				MAX
送り穴径 Dia. of driving hole	φ D ₀	4.0		4.0				±0.2
ボディの倒れ Off alignment of body top	Δh	2.0		2.0				MAX
テープの総厚み Sum of thickness for mounting and adhesive tape without lead dia	t	0.6		0.6				±0.3
梱包数量(個) Quantity (pcs)		2000 (φ8:1000)						

※個別に許容差が設定されている場合は、その数値が優先されます。

※For the case that tolerance is specified individually, the value shall have the priority.

◆テーピング仕様/TAPING SPECIFICATIONS



◆規格表/SPECIFICATION TABLE

項目 Item	記号 Code	9mm or more Height						※許容差 Tolerance		
		φ 5, φ 6.3		φ 8	φ 10	φ 12.5	φ 16		φ 18	
リード加工記号 Taping code		T1	TA	TA	T7	T8	G4	GC		
形状寸法図 Applicable Fig. No.		Fig.2	Fig.1	Fig.1	Fig.2	Fig.2	Fig.2	Fig.3		
リード線径 Dia. of lead	φ d	0.5		0.6			0.8		±0.05	
本体高さ Height of body	L	13.0		22.0		30.0		42.0		MAX
ボディーピッチ Distance from center to center of next body	P	12.7				15.0		30.0		±1.0
送り穴ピッチ Distance from center to center of next driving hole	P ₀	12.7				15.0		15.0±0.3		±0.2
送り穴位置ズレ (台紙上端との界面にて規定) Distance between center of driving hole and lead (at the upper edge of the carrier tape)	P ₁	5.1	3.85	4.6	3.85	5.0	3.75		±0.5	
送り穴位置ズレ Distance between center of driving hole and body	P ₂	6.35				7.5				±1.0
リードピッチ (台紙上端との界面にて規定) Pitch of lead (at the upper edge of the carrier tape)	F	2.5	5.0	3.5	5.0±0.8		7.5±0.8		+0.8 -0.2	
台紙幅 Width of mounting tape	W	18.0								±0.3
粘着テープ幅 Width of adhesive tape	W ₀	5.0								MIN
送り穴位置ズレ Distance between center of driving hole and mounting tape edge	W ₁	9.0								±0.5
粘着テープズレ Max. allowable distance between mounting and adhesive tape edges	W ₂	1.5								MAX
ボディ下面位置 Distance between center of driving hole and bottom of body	H	18.5		20.0		18.5 ^{+0.75} _{-0.5}				±0.75
リードクリンチ高さ Distance between center of driving hole and clinch part of lead	H ₀	-	16.0		-					±0.5
リード線はみ出し End of lead	L ₁	0.5								MAX
送り穴径 Dia. of driving hole	φ D ₀	4.0								±0.2
ボディの倒れ Off alignment of body top	Δh	2.0								MAX
テープの総厚み Sum of thickness for mounting and adhesive tape without lead dia	t	0.6								±0.3
梱包数量(個) Quantity (pcs)		2000		1000		500		250		

※個別に許容差が設定されている場合は、その数値が優先されます。

※For the case that tolerance is specified individually, the value shall have the priority.

◆リード線加工仕様／LEAD CUTTING FORMING SPECIFICATIONS

プリント基板取り付けが容易となる様、リードフォーミング、リードカットを行った製品及びプリント基板自立形用に特殊加工(キンクフォーミング)を行った製品を製造しております。

Rubycon provides lead-formed and lead-cut products to facilitate mounting on printed circuit boards, as well as products with leads specially processed (kink formed) for self supporting insertions to printed circuit boards.

・リードフォーミング
Lead forming
($\phi 5 \sim \phi 8$)
Lead forming code : FA

ϕD	5	6.3	8
ϕd	0.5		0.6
F	5.0		

・リードカット
Lead cutting
($\phi 5 \sim \phi 18$)
Lead cutting code : CA
CC
CE

ϕD	5	6.3	8	10	12.5	14.5	16	18
H	5.0.....(CA) 4.0.....(CC) 3.5.....(CE)							
ϕd	0.5		0.6		0.8			
F	2.0	2.5	3.5	5.0	7.5			

・キンクリードフォーミング
Kinked lead forming
($\phi 5 \sim \phi 8$)
Kinked lead forming code : KC

・キンクリードカット
Kinked lead forming
($\phi 10 \sim \phi 18$)
Kinked lead cutting code : KC

ϕD	5	6.3	8	10	12.5	14.5	16	18
H1	4.5							
H2	2.8							
H3	2.5		-					
F	5.0				7.5			
P	1.0							
E	1.2			1.3				
ϕd	0.5		0.6		0.8			

・横置き対応品 ($\phi 10 \sim \phi 18$) / Low profile with horizontal mounting

タイプA
Type A

タイプB
Type B

ϕD	10,12.5				14.5,16,18			
Code	RI	RK	RX	SG	RI	RK	RX	SG
ϕd	0.6				0.8			
F	5.0				7.5			
H	4.0		3.5		4.0		3.5	
Type	A	B	A	B	A	B	A	B